

MCC312 MCD312

Features

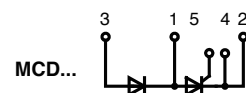
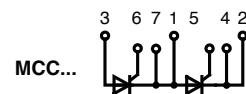
- ▶ International standard package,
- ▶ Direct copper bonded Al_2O_3 -ceramic with copper base plate
- ▶ Isolation voltage 3600 V~

Typical Applications

- ▶ Motor control,softstarter
- ▶ Power converter
- ▶ Light, heat and temperature control

Advantages

- ▶ Simple mounting
- ▶ Improved temperature and power cycling
- ▶ Reduced protection circuits



Symbol	MCC312-08io1 MCD312-08io1	MCC312-12io1 MCD312-12io1	MCC312-14io1 MCD312-14io1	MCC312-16io1 MCD312-16io1	MCC312-18io1 MCD312-18io1	Units
VRRM, VDRM	800	1200	1400	1600	1800	V
VRSM, VDSM	900	1300	1500	1700	1900	V

Symbol	Conditions	Values	Units
ITRMS, IFRMS	$T_{vj}=T_{vjM}$	520	A
ITAVM, IFAVM	sin.180; $T_c=85^\circ\text{C}$;	320	A
ITSM, IFSM	$T_{vj}=45^\circ\text{C}$; $t=10\text{ms}(50\text{Hz})$	9200	A
	$V_R=0$; $t=8.3\text{ms}(60\text{Hz})$	10100	A
	$T_{vj}=T_{vjM}$; $t=10\text{ms}(50\text{Hz})$	8000	A
	$V_R=0$; $t=8.3\text{ms}(60\text{Hz})$	8800	A
I ² t	$T_{vj}=45^\circ\text{C}$; $t=10\text{ms}(50\text{Hz})$	423000	A ² s
	$V_R=0$; $t=8.3\text{ms}(60\text{Hz})$	423000	A ² s
	$T_{vj}=T_{vjM}$; $t=10\text{ms}(50\text{Hz})$	320000	A ² s
	$V_R=0$; $t=8.3\text{ms}(60\text{Hz})$	321000	A ² s
(di/dt) _{cr}	$T_{vj} = T_{vjM}$ $f = 50 \text{ Hz}$; $t_p = 200 \mu\text{s}$; $V_D = 2/3 V_{DRM}$ $I_G = 1 \text{ A}$ $di_G / dt = 1 \text{ A}/\mu\text{s}$	repetitive, $I_T = 960 \text{ A}$	100 A/ μs
		non repetitive, $I_T = I_{TAVM}$	500 A/ μs
(dv/dt) _{cr}	$T_{vj} = T_{vjM}$; $V_D = 2/3 V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise)	1000	V/ μs
PGM	$T_{vj} = T_{vjM}$; $t_p = 30 \mu\text{s}$	120	W
PGAV	$I_T = I_{T(AV)M}$; $t_p = 500 \mu\text{s}$	60	W
		20	W
VRGM		10	V
T_{vj}		-40...+140	$^\circ\text{C}$
T_{vjM}		140	$^\circ\text{C}$
T_{stg}		-40...+125	$^\circ\text{C}$
V_{isol}	a.c.50Hz/60Hz; $I_{ISOL} < 1 \text{ mA}$ $t=1\text{s}/1\text{min.}$	3600/3000	V~
M_d	Mounting torque (M5)	4.5-7	Nm
	Terminal connection torque (M8)	11-13	Nm
Weight	Typical including screws	750	g

Symbol	Conditions	Values		Units
		typ.	max.	
I_{RRM}, I_{DRM}	$V_R/V_D = V_{RRM}/V_{DRM}$ $T_{Vj} = T_{VjM}$		40	mA
V_T, V_F	$I_T, I_F = 600A$ $T_{Vj} = 25^\circ C$		1.32	V
V_{T0}	For power-loss calculations only		0.80	V
r_t			0.68	mΩ
V_{GT}	$V_D = 6V$ $T_{Vj} = 25^\circ C$		2.0	V
	$T_{Vj} = -40^\circ C$		3.0	V
I_{GT}	$V_D = 6V$ $T_{Vj} = 25^\circ C$		150	mA
	$T_{Vj} = -40^\circ C$		200	mA
V_{GD}	$V_D = 2/3, V_{DRM}$ $T_{Vj} = T_{VjM}$		0.25	V
I_{GD}			10	mA
I_L	$t_p = 30 \mu s; V_D = 6V$ $T_{Vj} = 25^\circ C$ $I_G = 0.45A; di_G/dt = 0.45A/\mu s$		200	mA
I_H	$V_D = 6V; R_{GK} = \infty; T_{Vj} = 25^\circ C$		150	mA
t_{gd}	$V_D = 1/2 V_{DRM}$ $T_{Vj} = 25^\circ C$ $I_G = 1A; di_G/dt = 1A/\mu s$		2	μs
t_q	$V_D = 2/3 V_{DRM}$ $T_{Vj} = T_{VjM}$ $dv/dt = 50V/\mu s; -di/dt = 10A/\mu s$ $I_T = 300A; V_R = 100V; t_p = 200\mu s$	200		μs
Q_s	$I_T / I_F = 400A; -di/dt = 50A/\mu s$ $T_{Vj} = 125^\circ C$		760	μC
I_{RM}			275	A
R_{thJC}	per thyristor; DC current per module per thyristor; DC current per module } other values see Fig. 8/9		0.12	K/W
R_{thJK}			0.06	K/W
			0.16	K/W
			0.08	K/W
d_s	Creeping distance on surface		12.7	mm
d_A	Creepage distance in air		9.6	mm
a	Maximum allowable acceleration		50	m/s^2

Optional accessories for modules

Coded gate/cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red

Type **ZY 180L** (L = Left for pin pair 4/5) }
Type **ZY 180R** (R = Right for pin pair 6/7) } CSA class 5851, guide 460-1-1

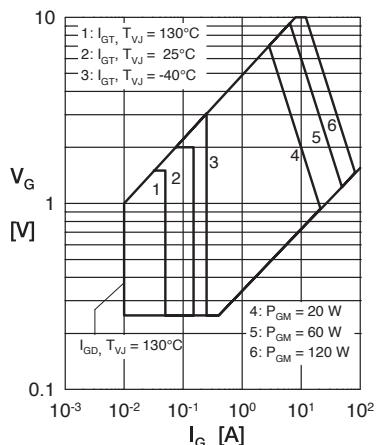


Fig. 1 Surge overload current
 $I_{TSM/FSM}$: Crest value, t : duration

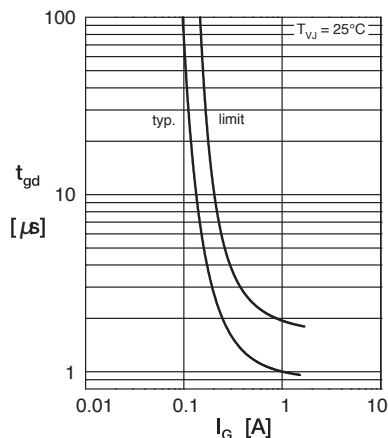


Fig. 2 Gate trigger delay time

MCC312 MCD312

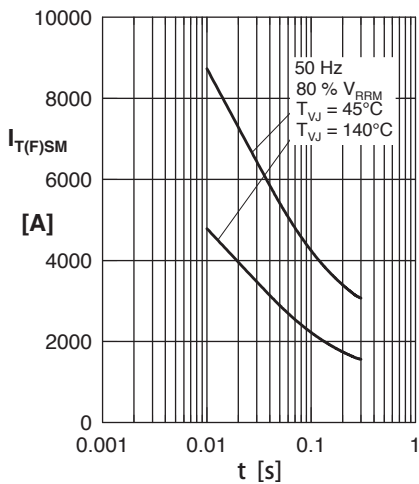


Fig. 3 Surge overload current
 $I_{T(F)SM}$: Crest value, t : duration

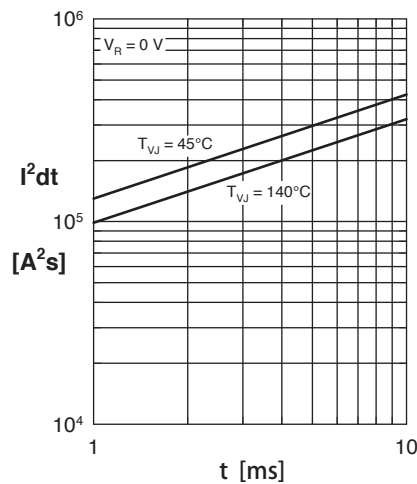


Fig. 4 I^2dt versus time

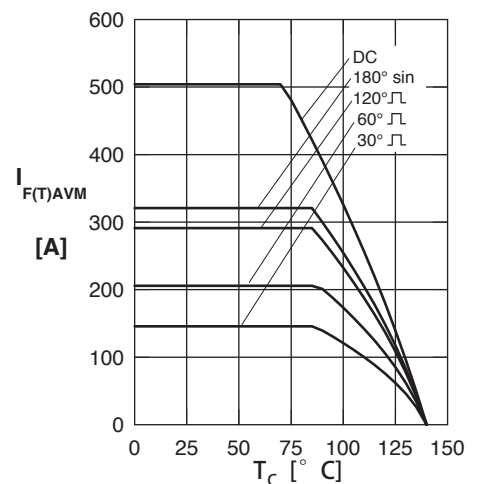


Fig. 4a Max. forward current
at case temperature

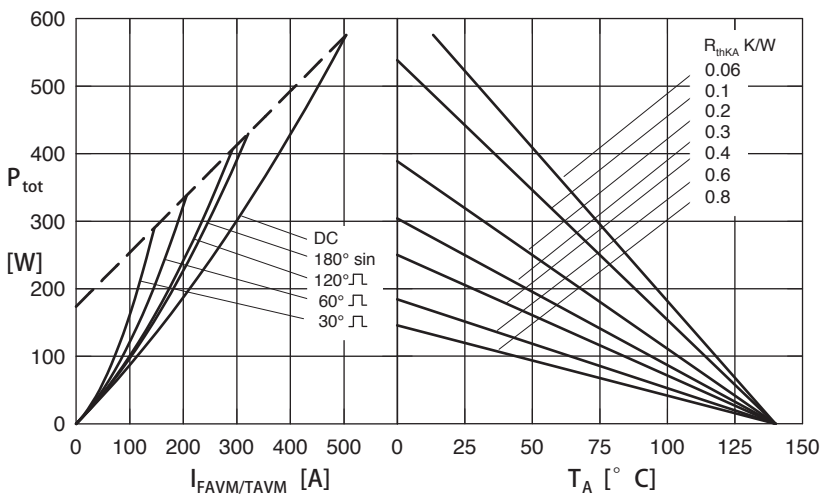


Fig. 5 Power dissipation versus on-state current and
ambient temperature (per thyristor or diode)

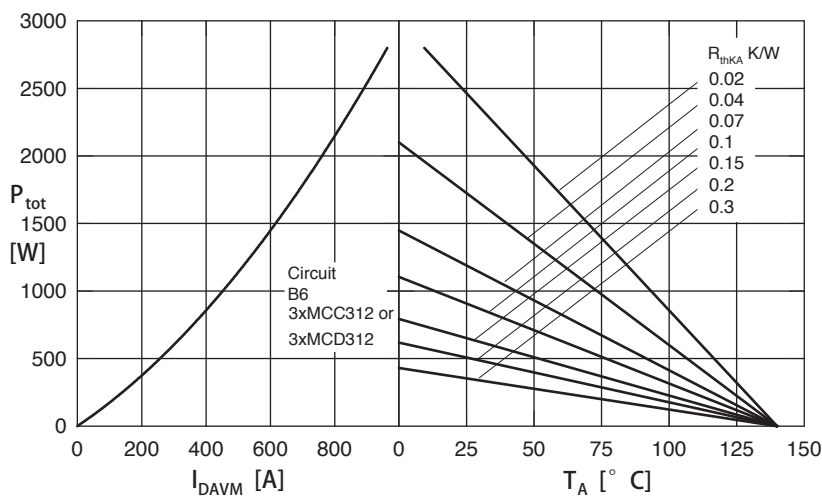


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct
output current and ambient temperature

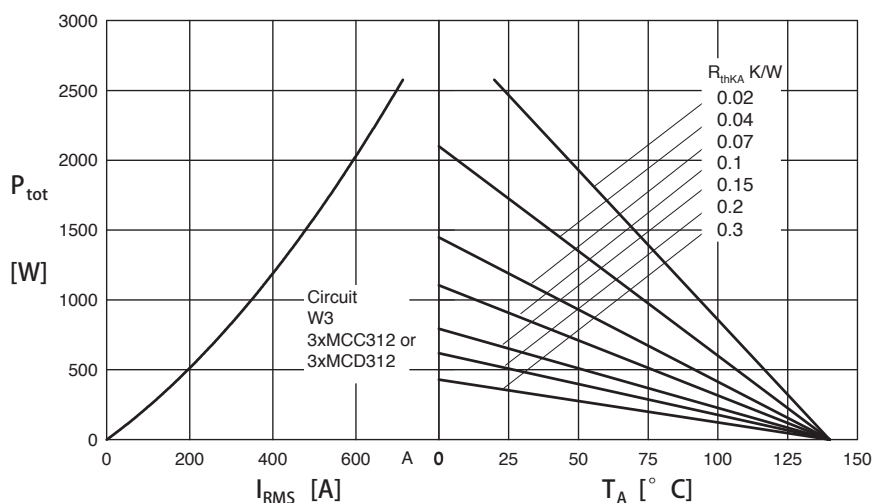


Fig. 7 Three phase AC-controller: Power dissipation versus R_{MS} output current and ambient temperature

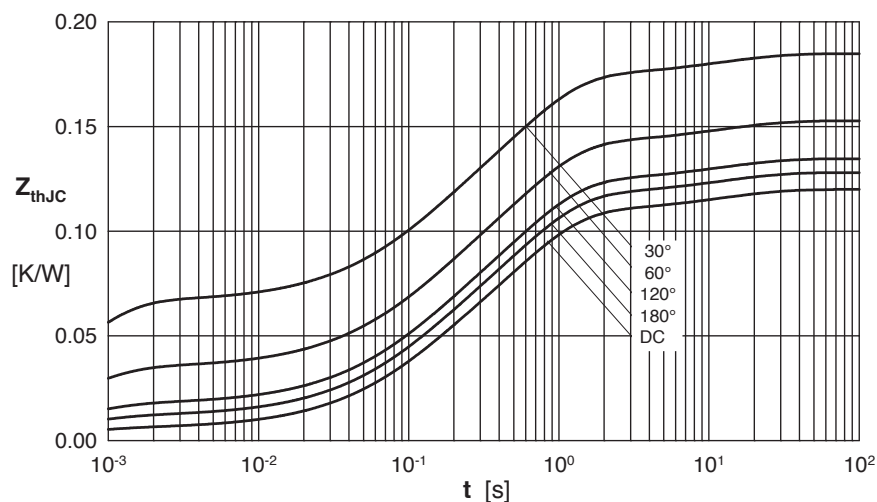


Fig. 8 Transient thermal impedance junction to case (per thyristor/diode)

R_{thJC} for various conduct. angles d:

d	R_{thJC} (K/W)
DC	0.120
180°	0.128
120°	0.135
60°	0.153
30°	0.185

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0058	0.00054
2	0.031	0.098
3	0.072	0.54
4	0.0112	12

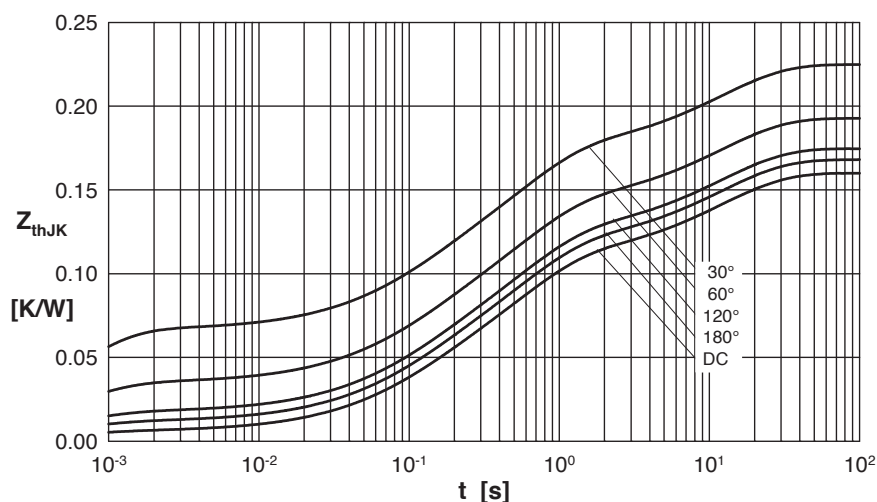


Fig. 9 Transient thermal impedance junction to heatsink (per thyristor/diode)

R_{thJK} for various conduct. angles d:

d	R_{thJK} (K/W)
DC	0.160
180°	0.168
120°	0.175
60°	0.193
30°	0.225

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0058	0.00054
2	0.031	0.098
3	0.072	0.54
4	0.0112	12
5	0.04	12

MCC312 MCD312

Dimensions in mm (1 mm = 0.0394")

